

SN74LVC574A-EP OCTAL EDGE-TRIGGERED D-TYPE FLIP-FLOP WITH 3-STATE OUTPUTS

SCAS750A-DECEMBER 2003-REVISED AUGUST 2005

FEATURES

Controlled Baseline

 One Assembly/Test Site, One Fabrication Site

- Extended Temperature Performance of -40°C to 125°C
- Enhanced Diminishing Manufacturing Sources (DMS) Support
- Enhanced Product-Change Notification
- Qualification Pedigree (1)
- Operates From 2 V to 3.6 V
- Inputs Accept Voltages to 5.5 V
- Max t_{pd} of 7 ns at 3.3 V
- Typical V_{OLP} (Output Ground Bounce) <0.8 V at V_{CC} = 3.3 V, T_A = 25°C
- Typical V_{OHV} (Output V_{OH} Undershoot) >2 V at V_{CC} = 3.3 V, T_A = 25°C
- (1) Component qualification in accordance with JEDEC and industry standards to ensure reliable operation over an extended temperature range. This includes, but is not limited to, Highly Accelerated Stress Test (HAST) or biased 85/85, temperature cycle, autoclave or unbiased HAST, electromigration, bond intermetallic life, and mold compound life. Such qualification testing should not be viewed as justifying use of this component beyond specified performance and environmental limits.

- Supports Mixed-Mode Signal Operation on All Ports (5-V Input/Output Voltage With 3.3-V V_{cc})
- I_{off} Supports Partial-Power-Down Mode Operation

DW OR PW PACKAGE (TOP VIEW)										
OE 1 20 Vcc 1D 2 19 1Q 2D 3 18 2Q 3D 4 17 3Q 4D 5 16 4Q 5D 6 15 5Q 6D 7 14 6Q 7D 8 13 7Q 8D 9 12 8Q GND 10 11 CL										

DESCRIPTION/ORDERING INFORMATION

The SN74LVC574A-EP octal edge-triggered D-type flip-flop is designed for 2.7-V to 3.6-V V_{CC} operation.

This device features 3-state outputs designed specifically for driving highly capacitive or relatively low-impedance loads. It is particularly suitable for implementing buffer registers, I/O ports, bidirectional bus drivers, and working registers.

On the positive transition of the clock (CLK) input, the Q outputs are set to the logic levels at the data (D) inputs.

A buffered output-enable (\overline{OE}) input can be used to place the eight outputs in either a normal logic state (high or low logic levels) or the high-impedance state. In the high-impedance state, the outputs neither load nor drive the bus lines significantly. The high-impedance state and increased drive provide the capability to drive bus lines without interface or pullup components.

OE does not affect the internal operations of the flip-flops. Old data can be retained or new data can be entered while the outputs are in the high-impedance state.

T _A	PACKAGE	(1)	ORDERABLE PART NUMBER	TOP-SIDE MARKING
-40°C to 125°C	SOIC – DW	Reel of 2000	SN74LVC574AQDWREP	C574AEP
	TSSOP – PW	Reel of 2000	SN74LVC574AQPWREP	C574AEP

ORDERING INFORMATION

(1) Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

SN74LVC574A-EP OCTAL EDGE-TRIGGERED D-TYPE FLIP-FLOP WITH 3-STATE OUTPUTS

TEXAS INSTRUMENTS www.ti.com

SCAS750A-DECEMBER 2003-REVISED AUGUST 2005

DESCRIPTION/ORDERING INFORMATION (CONTINUED)

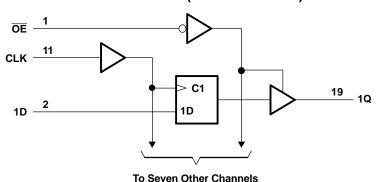
This device is fully specified for partial-power-down applications using I_{off}. The I_{off} circuitry disables the outputs, preventing damaging current backflow through the device when it is powered down.

To ensure the high-impedance state during power up or power down, \overline{OE} should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

Inputs can be driven from either 3.3-V or 5-V devices. This feature allows the use of this device as a translator in a mixed 3.3-V/5-V system environment.

FUNCTION TABLE (EACH FLIP-FLOP)

	INPUTS	OUTPUT	
ŌĒ	CLK	D	Q
L	\uparrow	Н	Н
L	\uparrow	L	L
L	L	х	Q ₀
Н	х	х	Z



LOGIC DIAGRAM (POSITIVE LOGIC)

SCAS750A-DECEMBER 2003-REVISED AUGUST 2005

Absolute Maximum Ratings⁽¹⁾

over operating free-air temperature range (unless otherwise noted)

			MIN	MAX	UNIT
V _{CC}	Supply voltage range		-0.5	6.5	V
VI	Input voltage range ⁽²⁾	-0.5	6.5	V	
Vo	Voltage range applied to any output in the high-imp	-0.5	6.5	V	
Vo	Voltage range applied to any output in the high or I	-0.5	V _{CC} + 0.5	V	
I _{IK}	Input clamp current	V ₁ < 0		-50	mA
I _{OK}	Output clamp current	V _O < 0		-50	mA
I _O	Continuous output current			±50	mA
	Continuous current through V_{CC} or GND			±100	mA
0	Deckage thermal impedance (4)	DW package		58	°C/W
θ_{JA}	Package thermal impedance ⁽⁴⁾		83	-0/00	
T _{stg}	Storage temperature range ⁽⁵⁾		-65	150	°C

(1) Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

(2) The input and output negative-voltage ratings may be exceeded if the input and output current ratings are observed.

(3) The value of V_{CC} is provided in the recommended operating conditions table.

(4) The package thermal impedance is calculated in accordance with JESD 51-7.

(5) Long-term high-temperature storage and/or extended use at maximum recommended operating conditions may result in a reduction of overall device life. See http://www.ti.com/ep_quality for additional information on enhanced plastic packaging.

Recommended Operating Conditions⁽¹⁾

			MIN	MAX	UNIT
V	Supply veltage	Operating	2	3.6	V
V _{CC}	Supply voltage	Data retention only	1.5		v
V _{IH}	High-level input voltage	$V_{CC} = 2.7 V \text{ to } 3.6 V$	2		V
V _{IL}	Low-level input voltage	V _{CC} = 2.7 V to 3.6 V		0.8	V
VI	Input voltage		0	5.5	V
V	Output veltage	High or low state	0	V _{CC}	V
Vo	Output voltage	3-state	0	5.5	v
	Ligh lovel output ourrest	V _{CC} = 2.7 V		-12	~ ^
юн	High-level output current	$V_{CC} = 3 V$		-24	mA
		V _{CC} = 2.7 V		12	~ ^
I _{OL}	Low-level output current		24	mA	
$\Delta t/\Delta v$	Input transition rise or fall rate	· ·		6	ns/V
T _A	Operating free-air temperature		-40	125	°C

 All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.

SN74LVC574A-EP **OCTAL EDGE-TRIGGERED D-TYPE FLIP-FLOP** WITH 3-STATE OUTPUTS

SCAS750A-DECEMBER 2003-REVISED AUGUST 2005

Electrical Characteristics

over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	V _{cc}	MIN TYP ⁽¹⁾ MAX	UNIT
	I _{OH} = -100 μA	2.7 V to 3.6 V	V _{CC} - 0.2	
	10	2.7 V	2.2	v
V _{OH}	$I_{OH} = -12 \text{ mA}$	3 V	2.4	v
	$I_{OH} = -24 \text{ mA}$	3 V	2.2	
	I _{OL} = 100 μA	2.7 V to 3.6 V	0.2	
V _{OL}	I _{OL} = 12 mA	2.7 V	0.4).4 V
	I _{OL} = 24 mA	3 V	0.55	
I _I	V _I = 0 to 5.5 V	3.6 V	±5	μA
I _{OZ}	V _O = 0 to 5.5 V	3.6 V	±15	μΑ
I	$V_{I} = V_{CC}$ or GND	3.6 V	10	۸
I _{CC}	$I_{\rm O} = 0$ 3.6 V ≤ V ₁ ≤ 5.5 V ⁽²⁾	5.0 V	10	μA
ΔI_{CC}	One input at V_{CC} – 0.6 V, Other inputs at V_{CC} or GND	2.7 V to 3.6 V	500	μΑ
C _i	$V_{I} = V_{CC}$ or GND	3.3 V	4	pF
Co	$V_{O} = V_{CC}$ or GND	3.3 V	5.5	pF

All typical values are at V_{CC} = 3.3 V, T_A = 25^{\circ}C. This applies in the disabled state only. (1)

(2)

Timing Requirements

over recommended operating free-air temperature range (unless otherwise noted) (see Figure 1)

		V _{CC} =	2.7 V	V _{CC} = 2 ± 0.3	UNIT	
		MIN	MAX	MIN	MAX	
f _{clock}	Clock frequency		150		150	MHz
t _w	Pulse duration, CLK high or low	3.3		3.3		ns
t _{su}	Setup time, data before CLK1	2		2		ns
t _h	Hold time, data after CLK↑	2		2		ns

Switching Characteristics

over recommended operating free-air temperature range (unless otherwise noted) (see Figure 1)

PARAMETER		TO (OUTPUT)	V _{CC} =	2.7 V	V _{CC} = 2 ± 0.3	UNIT	
	(INPUT)	(001F01)	MIN	MAX	MIN	MAX	
f _{max}			150		150		MHz
t _{pd}	CLK	Q		8	1	7	ns
t _{en}	OE	Q		9	1	7.5	ns
t _{dis}	OE	Q		7	0.5	6.4	ns

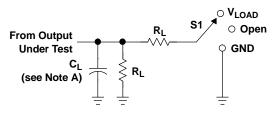
Operating Characteristics

 $T_A = 25^{\circ}C$

	PARAMETER	TEST CONDITIONS	V _{CC} = 2.5 V TYP	V _{CC} = 3.3 V TYP	UNIT		
<u> </u>	Device dissipation consolitance can flip flop	Outputs enabled	£ 10 MUL	60	43	- 5	
C _{pd} I	Power dissipation capacitance per flip-flop	Outputs disabled	f = 10 MHz	9	15	pF	

SCAS750A-DECEMBER 2003-REVISED AUGUST 2005

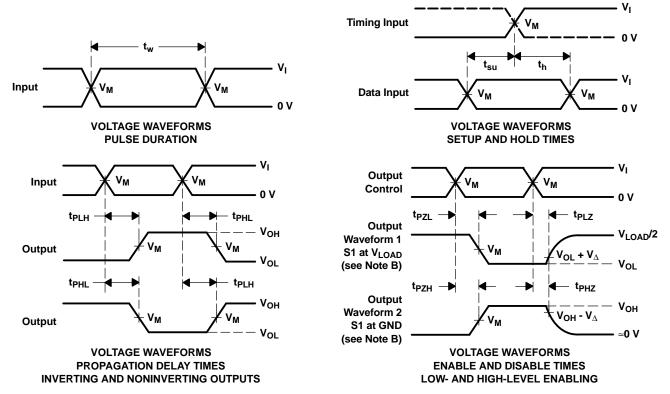
PARAMETER MEASUREMENT INFORMATION



TEST	S1
t _{PLH} /t _{PHL}	Open
t _{PLZ} /t _{PZL}	V _{LOAD}
t _{PHZ} /t _{PZH}	GND

LOAD CIRCUIT

	INF	PUTS			•	-	
V _{CC}	VI	t _r /t _f	V _M	V _{LOAD}	CL	RL	V_{Δ}
2.7 V	2.7 V	≤2.5 ns	1.5 V	6 V	50 pF	500 Ω	0.3 V
3.3 V \pm 0.3 V	2.7 V	≤2.5 ns	1.5 V	6 V	50 pF	500 Ω	0.3 V



- NOTES: A. CL includes probe and jig capacitance.
 - B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control. C. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, Z_O = 50 Ω .
 - D. The outputs are measured one at a time, with one transition per measurement.
 - E. t_{PLZ} and t_{PHZ} are the same as t_{dis} .

 - F. t_{PZL} and t_{PZH} are the same as t_{en} . G. t_{PLH} and t_{PHL} are the same as t_{pd} .
 - H. All parameters and waveforms are not applicable to all devices.

Figure 1. Load Circuit and Voltage Waveforms



10-Dec-2020

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead finish/ Ball material (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
SN74LVC574AQPWREP	ACTIVE	TSSOP	PW	20	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 125	C574AEP	Samples
V62/04668-01YE	ACTIVE	TSSOP	PW	20	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 125	C574AEP	Samples

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

⁽²⁾ RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (CI) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <= 1000ppm threshold. Antimony trioxide based flame retardants must also meet the <= 1000ppm threshold requirement.

⁽³⁾ MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

⁽⁴⁾ There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

⁽⁵⁾ Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

⁽⁶⁾ Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

Important Information and Disclaimer:The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.



www.ti.com

PACKAGE OPTION ADDENDUM

10-Dec-2020

OTHER QUALIFIED VERSIONS OF SN74LVC574A-EP :

- Catalog: SN74LVC574A
- Automotive: SN74LVC574A-Q1
- Military: SN54LVC574A

NOTE: Qualified Version Definitions:

- Catalog TI's standard catalog product
- Automotive Q100 devices qualified for high-reliability automotive applications targeting zero defects
- Military QML certified for Military and Defense Applications

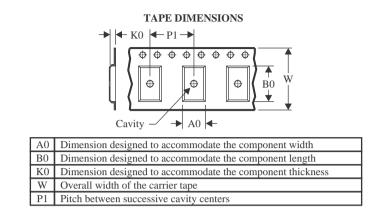


TEXAS

STRUMENTS

TAPE AND REEL INFORMATION





QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal													
	Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
	SN74LVC574AQPWREP	TSSOP	PW	20	2000	330.0	16.4	6.95	7.0	1.4	8.0	16.0	Q1



www.ti.com

PACKAGE MATERIALS INFORMATION

3-Jun-2022



*All	dimensions	are	nominal	
------	------------	-----	---------	--

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74LVC574AQPWREP	TSSOP	PW	20	2000	356.0	356.0	35.0

IMPORTANT NOTICE AND DISCLAIMER

TI PROVIDES TECHNICAL AND RELIABILITY DATA (INCLUDING DATA SHEETS), DESIGN RESOURCES (INCLUDING REFERENCE DESIGNS), APPLICATION OR OTHER DESIGN ADVICE, WEB TOOLS, SAFETY INFORMATION, AND OTHER RESOURCES "AS IS" AND WITH ALL FAULTS, AND DISCLAIMS ALL WARRANTIES, EXPRESS AND IMPLIED, INCLUDING WITHOUT LIMITATION ANY IMPLIED WARRANTIES OF MERCHANTABILITY, FITNESS FOR A PARTICULAR PURPOSE OR NON-INFRINGEMENT OF THIRD PARTY INTELLECTUAL PROPERTY RIGHTS.

These resources are intended for skilled developers designing with TI products. You are solely responsible for (1) selecting the appropriate TI products for your application, (2) designing, validating and testing your application, and (3) ensuring your application meets applicable standards, and any other safety, security, regulatory or other requirements.

These resources are subject to change without notice. TI grants you permission to use these resources only for development of an application that uses the TI products described in the resource. Other reproduction and display of these resources is prohibited. No license is granted to any other TI intellectual property right or to any third party intellectual property right. TI disclaims responsibility for, and you will fully indemnify TI and its representatives against, any claims, damages, costs, losses, and liabilities arising out of your use of these resources.

TI's products are provided subject to TI's Terms of Sale or other applicable terms available either on ti.com or provided in conjunction with such TI products. TI's provision of these resources does not expand or otherwise alter TI's applicable warranties or warranty disclaimers for TI products.

TI objects to and rejects any additional or different terms you may have proposed.

Mailing Address: Texas Instruments, Post Office Box 655303, Dallas, Texas 75265 Copyright © 2022, Texas Instruments Incorporated